

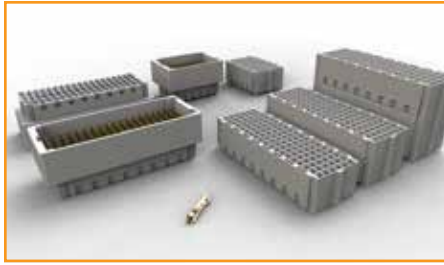


Mezalok Connectors

High-Reliability Mezzanine Connectors for VITA 61 (XMC 2.0)

Mezalok Connectors

High-Reliability Mezzanine Connectors



VERSATILE

- 114-position module is VITA 61 compliant
- 60, 114, and 320 positions
- 10, 12, 15, 17 and 18 mm stack heights

ROBUST

- Rugged surface-mount mezzanine connector with 500 mating cycle durability
- Improved thermal cycling stability compared to VITA 42 connectors—2000 thermal shock cycles -55°C to +125°C
- Supports data rates up to 16+ Gb/s
- Anti-stubbing design during mating

HIGH PERFORMANCE

- Mini-Box contact system provides four points of contact for ultra-reliability
- LCP plastic housings offer superior thermal stability and low outgassing
- Compliant BGA board-attach supports standard surface mount processing and excellent thermal stability

VITA 61 Mezalok (XMC 2.0) Connectors

TE's Mezalok mezzanine connectors are designed for stacking or mezzanine applications for rugged embedded computing. The connectors incorporate a quad-redundant Mini-Box contact system for a separable interface, and are available in 60, 114, and 320 positions with stack height options of 10, 12, 15, 17 and 18 mm.

Mezalok connectors are shock and vibration resistant per VITA 47 and 72 HALT test requirements. The 114-position connector is compliant to VITA 61. Featuring a wide operating temperature range, excellent thermal stability, and data rates to 16+ Gb/s, these rugged and highly versatile connectors are ideal for high-speed embedded computing applications. Installation of Mezalok connectors is easily accomplished using standard BGA surface mount processes.

STANDARDS AND SPECIFICATIONS

- **Application Specification:** 114-13279
- **Product Specification:** 108-2411
- **Qualification Test Report:** 501-736
- **Electrical Performance Report:** 505-4

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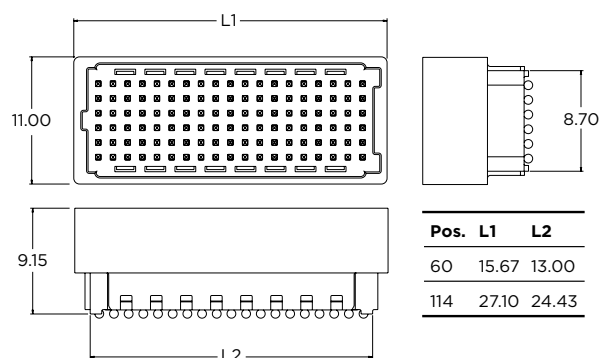
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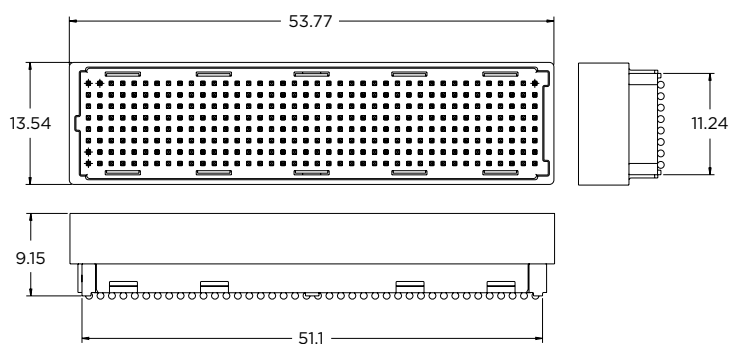
Mini-Box contact

Position Size	Connector and Stack Height (mm)	50 Microinch Gold Mating		30 Microinch Gold Mating	
		Tin-Lead BGA	Lead Free BGA	Tin-Lead BGA	Lead Free BGA
114 (XMC 2.0 per VITA 61)	Pin Connector	2102060-1	2102060-2	2102060-3	2102060-4
	Socket Connector	10	2102061-1	2102061-2	2102061-5
		12	2102061-3	2102061-4	2102061-7
		15	1-2102061-3	1-2102061-4	1-2102061-5
		17	1-2102061-7	1-2102061-8	1-2102061-6
		18	2102061-9	1-2102061-0	1-2102061-1
320	Pin Connector	2102429-1			2102429-4
	Socket Connector	10	2102430-1		2102430-6
		18	2102430-9		1-2102430-2
60	Pin Connector	2102079-1	2102079-2		
	Socket Connector	10	2102080-1	2102080-2	
		12	2102080-3	2102080-4	

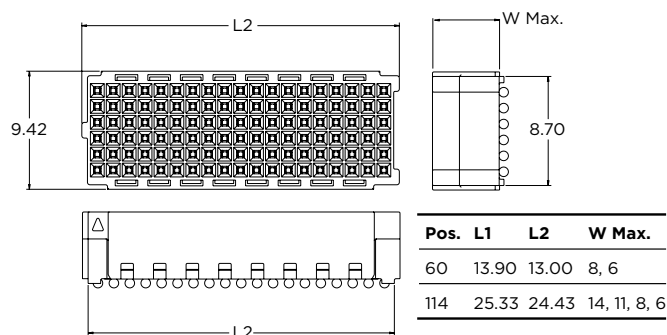
Pin — 60 position and 114 position



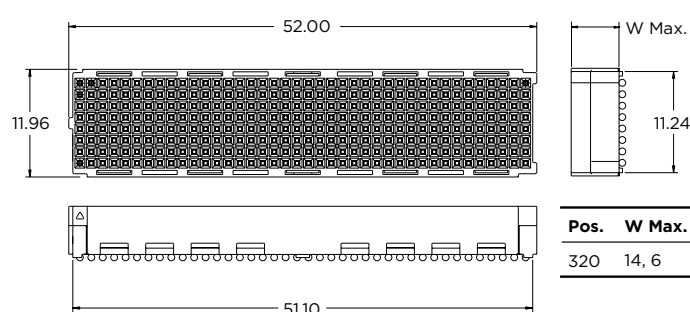
320 position



Socket — 60 position and 114 position



320 position



LET'S CONNECT

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